

Electrically Coupled Angular Decoder for Long-Life Mechanisms

Final Review

ESA Contract: 4000124988/18/NL/BJ/gp February 21th, 2020



- 1. Welcome and presentation of participants.
- 2. Review of the project and presentation of the tests results: project conclusions.
- 3. Discussion of RIDs.
- 4. Review of closure documents.
- 5. Review of follow up actions and roadmap
- 6. AoB.

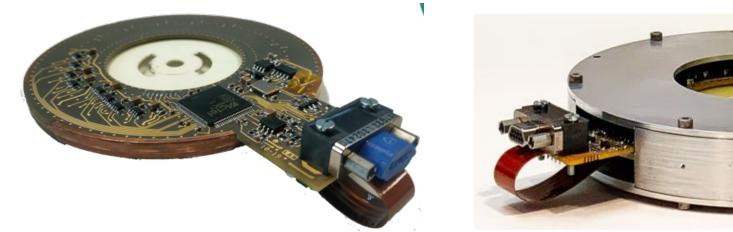


OBJECTIVE

Results from ESA Contract No. 4000124988/18/NL/BJ/gp "Electrically Coupled Angular Encoder for Long-Life Mechanisms" and ARTES 5.2 contract 4000104613/12/NL/AD "Electrically Coupled Angular Encoder for Long-Life Mechanisms", whose objectives are to provide the space industry with a medium resolution (16-bits) ECSS compliant angular sensor.

Main contributions of this project are:

- Redesign with hardware differences are listed in TN30 Annex 5
- Firmware modification with differences are listed in TN50 § 6
- Test plan & test results to evidence required functioning of the sensor



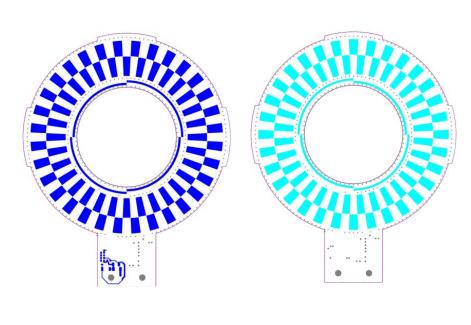




Summary of results (i):

emxys le electronics due to use of current nulling technique: sinusoidal voltages within the sensor do not produce synchro/resolver processing.

 Patent pending electrical coupling structure



Description

the sensor in terms of measurement capability, since

Modification

No redundancy

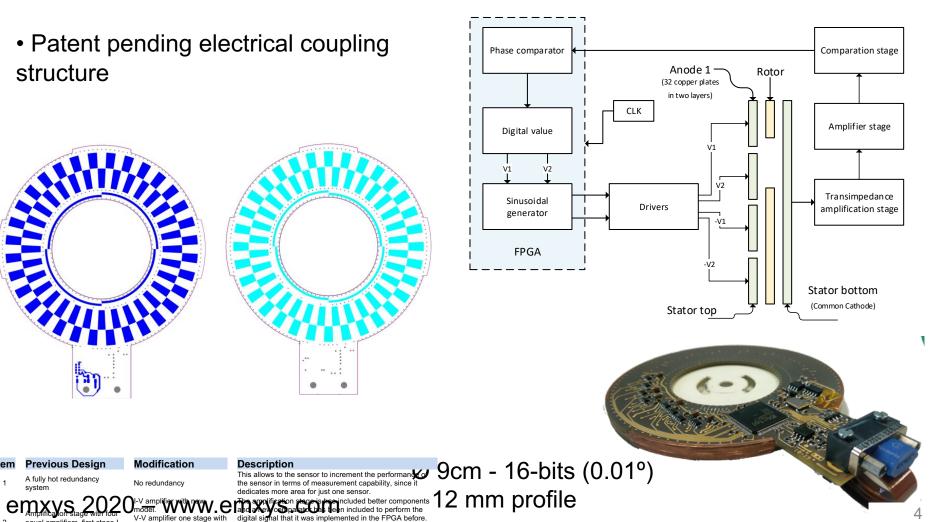
ltem

(C)

Previous Design

A fully hot redundancy

system





Delivered documents for RR:

TN10: Mechanical, Interface and Electrical specification.

Analysis of requirements in applicable documentation. Update and Consolidation of Specification Update of design description.

TN20: Test Equipment Specification and Verification Plan.

Establish a Design and Development approach in line with schedule constraints.

Delivered documents for DR:

TN30: CLAS Detailed Design

Detailed design of contactless sensor

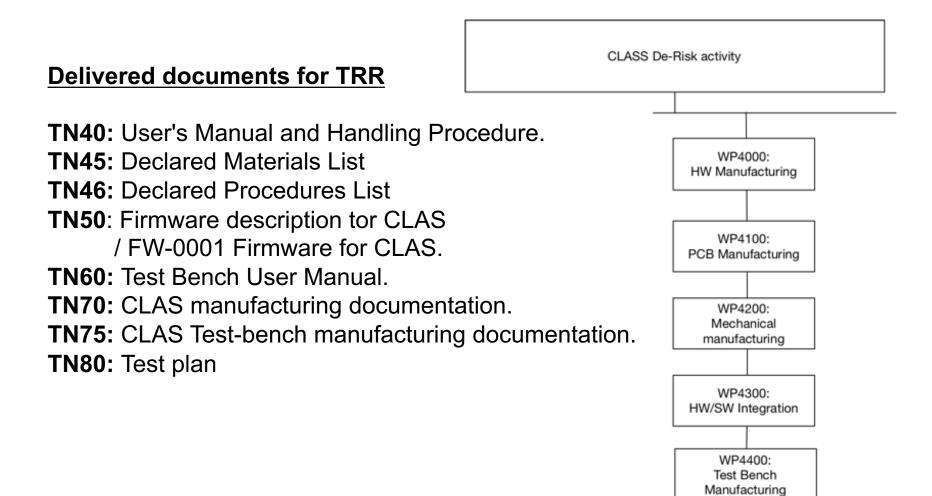
DP1: CLAS sensor design pack

Sensor schematics and GERBERs for sensor 3D mechanical CADs for sensor Mechanical manufacturing files for sensor

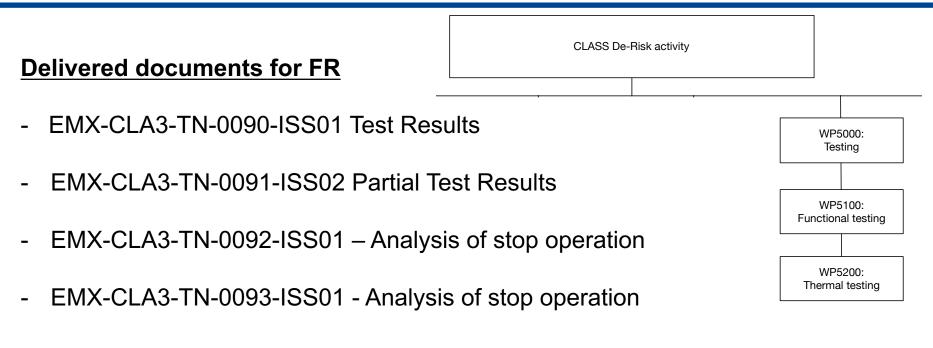
DP2: Test bench design pack

Sensor schematics and GERBERs for test bench 3D mechanical CADs for test bench Mechanical manufacturing files for test bench









RIDs documents to review

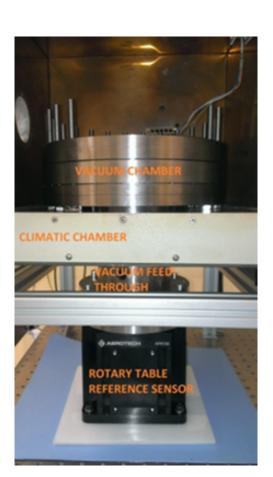
EMX-CLA3-RID-0001-ISS04_RRMeeting EMX-CLA3-RID-0002-ISS04 DR EMX-CLA3-RID-0003-ISS02 TRR EMX-CLA3-RID-0004-ISS01 FR



- Absolute angle encoding with no mechanical contact.
- Adaptable to any outer and inner shaft diameter: Ø 10cm (with enclosure) 16-bits (0.01°).
- Low profile: 20mm with enclosure.
- Flexible digital interface in parallel or serial form.
- Serial communication RS-485/RS-422. Available CAN or LVDS interfaces upon request.
- Analog (2-wire) interface realizable in the same electronic design.
- Single supply and very low power consumption <2W (+5.0V).
- Extended temperature range (-55C to +90C), and operational in radiation environments.
- Qualified electronics and materials for Space, military or aeronautical applications.
- FPGA based conditioning electronics. All electronics included in the enclosure.

Test bench development for angular sensors environmental characterization







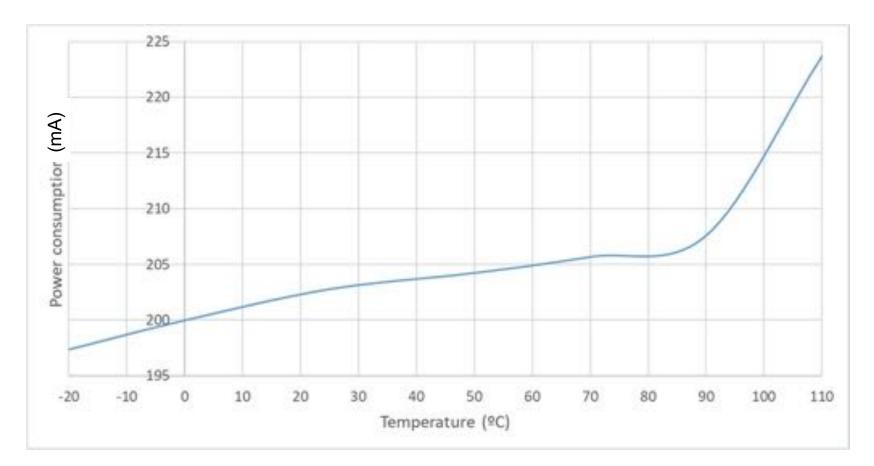


2. Review of the project



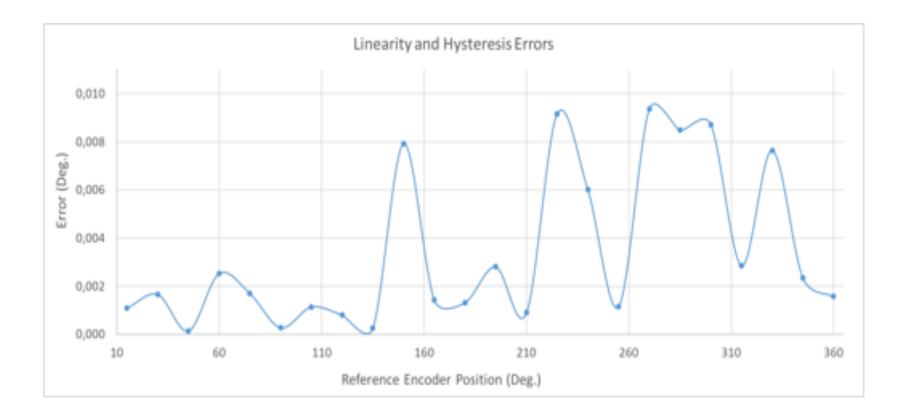


Test result - Consumption





Test result - Linearity and hysteresis errors (23° C)



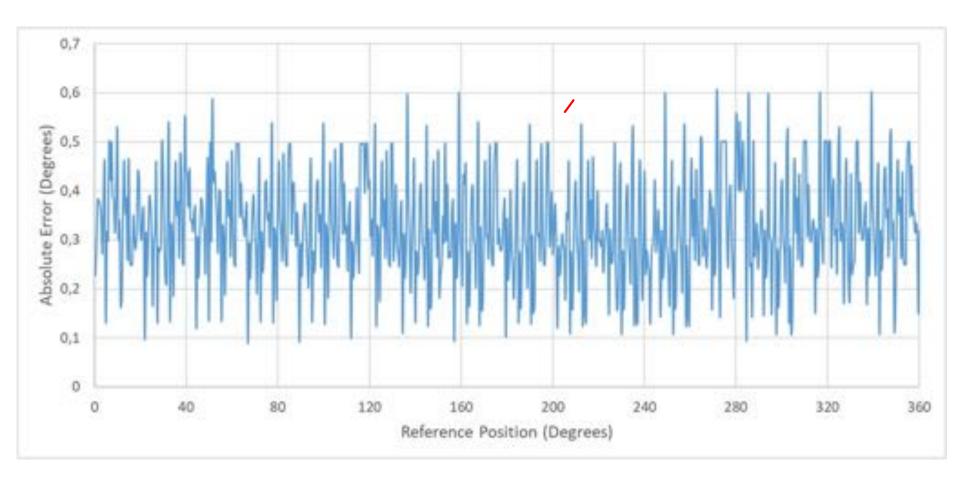


Test result - Repeatability (23°C)





Test result – Temperature measurement error







Unique

Requirement

Compliance Remarks and Statement

Test result – NC analysis

CLAS3_030	Measurement accuracy is ±0.01°	Partially C	See §3.7 and §3.8
CLAS3_040	Maximum supported speed 25º/second	TBD	To be verified.

CLAS3_060	Temperature stability < 50ppm/°C	NC	Results are not definitive due to testbench mechanical issues
	Requirement	Compliance Statement	Not verified within this project but verified in [RD2]
CLAS3_310	Acceptance temperature should be within a range -55°C to +70°C in compliance to ECSS-Q-ST-30-11C Rev 1.		Not verified within this project but verified in [RD2]



Review of RIDs to delivered documentation.

RIDs in previous EXCEL archives:

- EMX-CLA3-RID-0001-ISS03_RRMeeting (CLOSED)
- EMX-CLA3-RID-0002-ISS03_DR (CLOSED)
- EMX-CLA3-RID-0003-ISS02_TRR (Actions closed, to be reviewed)

RIDs for FR:

- EMX-CLA3-RID-0004-ISS01_FR



Closure configuration control is listed in

- See document EMX-CLA3-CCD-ISS01 Contract Closure Documentation



Roadmap:

- Develop three angular sensors for terrestrial aeronautical, defense and terrestrial applications. (timeframe 2020)
 - Ø 6cm 12-bits (0.1°).
 - Ø 9cm 16-bits (0.01°).
 - Ø 15cm 19-bits (0.001°).
- Reach TRL9 with a flight opportunity and follow the line of three sensors described above.

<u>Actions:</u>

- ESA Open Space Innovation Platform OSIP (10k CCN for market and applicability study) - Submitted
- ESA ESA AO/1-10147/20/NL/MH Invitation to Tender for Announcement of Opportunity for Technology Transfer Proof of Concepts (28/2 deadline) – 6 months study
- GVA project (timeframe)



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 - Sensor modifications for cost competitive solution
 - Prototype implementation
 - Test
- GVA project (12 months starting 01/04)
 - Sensor product line implementation
 - Promotion & market activities



- Contactless angular sensor ECSS compliant; FMECA, PSA, WCA available; No catastrophic failures guaranteed.
- Error within 0.01° (16 bits) for -55°C to +90°C after calibration
- +5V supply, 2.25W worst case consumption, RS485 interface
- All electronics within the enclosure
- Our aim is to set a market product in early 2021.